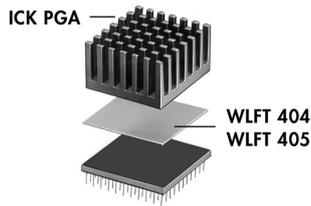


Data sheet Product ICK PGA 11 x 11 x 12



Heatsinks and active heatsinks for processors>Heatsinks for PGA
27.95 x 24.76 x 12.5 mm, for IC design PGA and others

Features

way of fixation:	<ul style="list-style-type: none"> • therm. conductive foil • therm. cond. adhesive
socket:	universal
suitable for processor type:	universal
width:	27.95 mm
height:	12.5 mm
plate thickness:	3.5 mm
length:	24.76 mm
thermal resistance:	12.3 - 3 K/W
dissipation loss:	3.9 W
surface:	black anodised

Technical Drawing

